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Speech subject： Research on Cu/SiO2 Hybrid Bonding for Chiplet Integration

Speech leader: *Junpeng FANG, School of Integrated Circuits, Tsinghua University*

Speech Description/Objective:

Speech Outline:

Who Should Attend:

Introduction of Speaker:

Junpeng FANG graduated from the School of Integrated Circuits, Tsinghua University with a PhD in engineering. He is engaged in the research of advanced packaging and system integration, including hybrid bonding process research, nano interconnect and chiplet integration process research, and interconnection reliability and failure mechanism analysis. At present, he has published many articles in important academic journals and high-level international conferences at home and abroad, such as Applied Surface Science, IEEE EDL, IEEE TED, ECTC, etc.